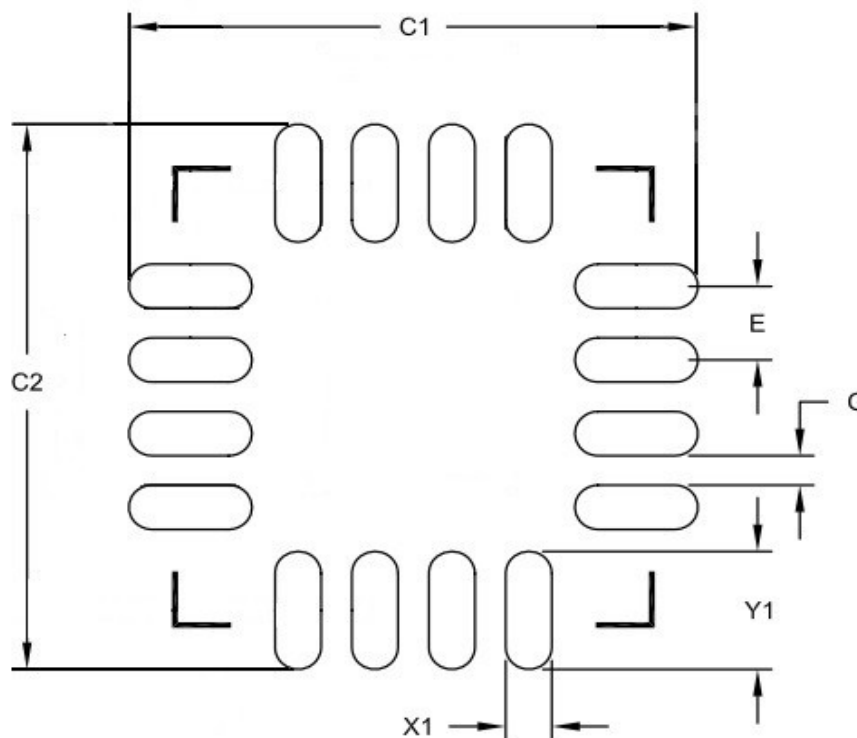


## LGA16 3x3mm 0.5mm - stencil

		Units	MILLIMETERS		
Dimension Limit			MIN	NOM	MAX
Contact Pitch	E		0.50		
Contact Pad Spacing	C1,C2			3.65	
Contact Pad Width	X1			0.18	
Contact Pad Length	Y1			0.58	
Distance Between Pads	G			0.32	

### Top View (SMD Footprint)



Stencil dimensions: 38mm x 28mm

Thickness: 100-127 $\mu$ m

Material: stainless steel or nickel silver

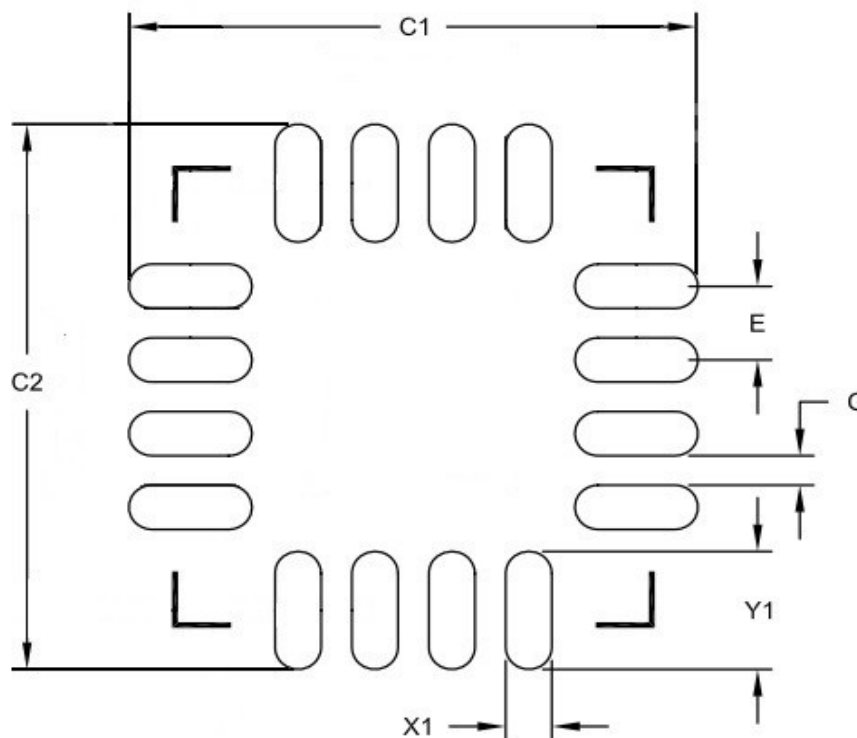
Manufacturing processes: lasering or chemical etching

Datasheet rev.: 1.04

## LGA16 5x5mm 0.8mm - stencil

		Units	MILLIMETERS		
Dimension Limit			MIN	NOM	MAX
Contact Pitch	E		0.80		
Contact Pad Spacing	C1,C2			5.00	
Contact Pad Width	X1			0.42	
Contact Pad Length	Y1			0.92	
Distance Between Pads	G			0.38	

### Top View (SMD Footprint)



Stencil dimensions: 38mm x 28mm

Thickness: 100-127 $\mu$ m

Material: stainless steel or nickel silver

Manufacturing processes: lasering or chemical etching

Datasheet rev.: 1.04